

SEMICONDUCTOR PACKAGE AND FABRICATING METHOD THEREOF

ABSTRACT OF THE DISCLOSURE

A semiconductor package and a fabricating method thereof are proposed. The semiconductor package includes a semiconductor chip; a plurality of leads surrounding the chip and formed with a plurality of connecting mechanisms and strengthening structures; and an encapsulant for encapsulating the chip and the leads. The foregoing semiconductor package eliminates the use of a die pad, allowing the thickness of the package to be reduced and a surface of the chip to be exposed to the outside of the encapsulant for improving the heat dissipating efficiency thereof. The leads have the same height as the semiconductor package, allowing upper and lower surfaces of the leads to be exposed to the outside of the encapsulant, which further enhance the dissipation of heat generated by the chip in operation. The strengthening structures of the leads significantly enhance the bonding strength between the leads and the encapsulant for preventing delamination or crack from occurrence, so that quality and liability of the semiconductor package can be assured.

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